



SOT369-1

plastic shrink small outline package; 16 leads; body width 4.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SSOP16
Package type industry code	SSOP16
Package style descriptive code	SSOP (shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-152
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

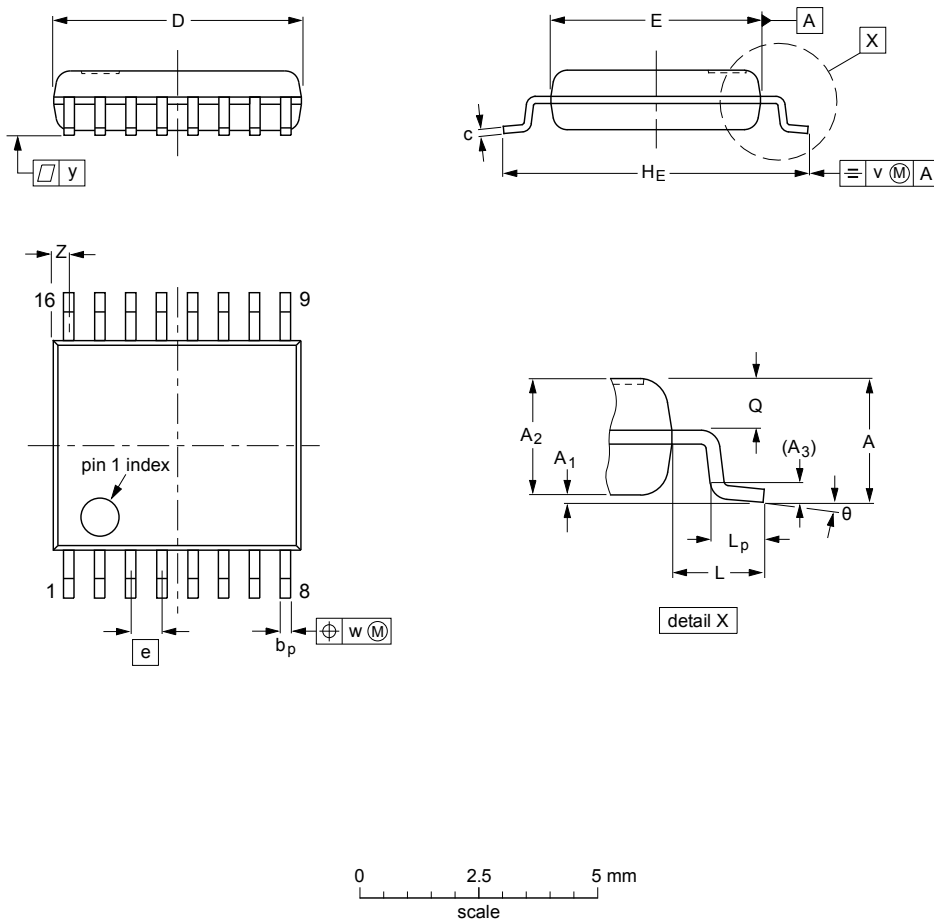
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.1	-	5.2	5.3	mm
E	package width	4.3	-	4.4	4.5	mm
A	seated height	[tbd]	-	1.5	1.5	mm
A ₂	package height	1.2	-	1.3	1.4	mm
n ₂	actual quantity of termination	-	-	16	-	



2. Package outline

SSOP16: plastic shrink small outline package; 16 leads; body width 4.4 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1.5	0.15 0.00	1.4 1.2	0.25	0.32 0.20	0.25 0.13	5.3 5.1	4.5 4.3	0.65	6.6 6.2	1	0.75 0.45	0.65 0.45	0.2	0.13	0.1	0.48 0.18	10° 0°

Note

1. Plastic or metal protrusions of 0.2 mm maximum per side are not included.

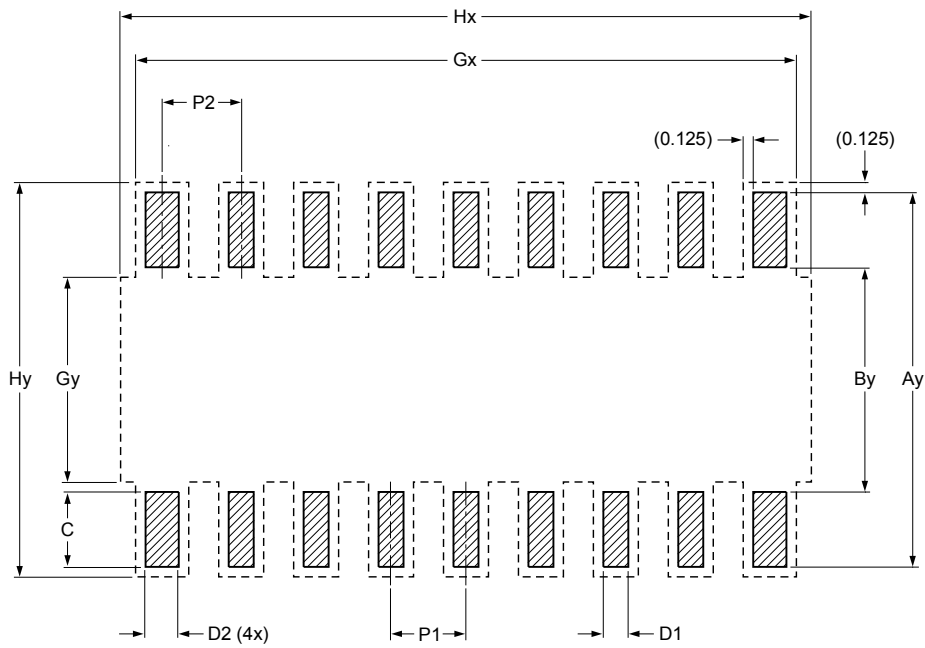
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT369-1		MO-152				99-12-27 03-02-19

Fig. 1. Package outline SSOP16 (SOT369-1)


3. Soldering

Footprint information for reflow soldering of SSOP16 package

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Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land
- - - - occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.750	7.200	4.500	1.350	0.400	0.600	5.600	5.300	5.800	7.450

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Fig. 2. Reflow soldering footprint for SSOP16 (SOT369-1)

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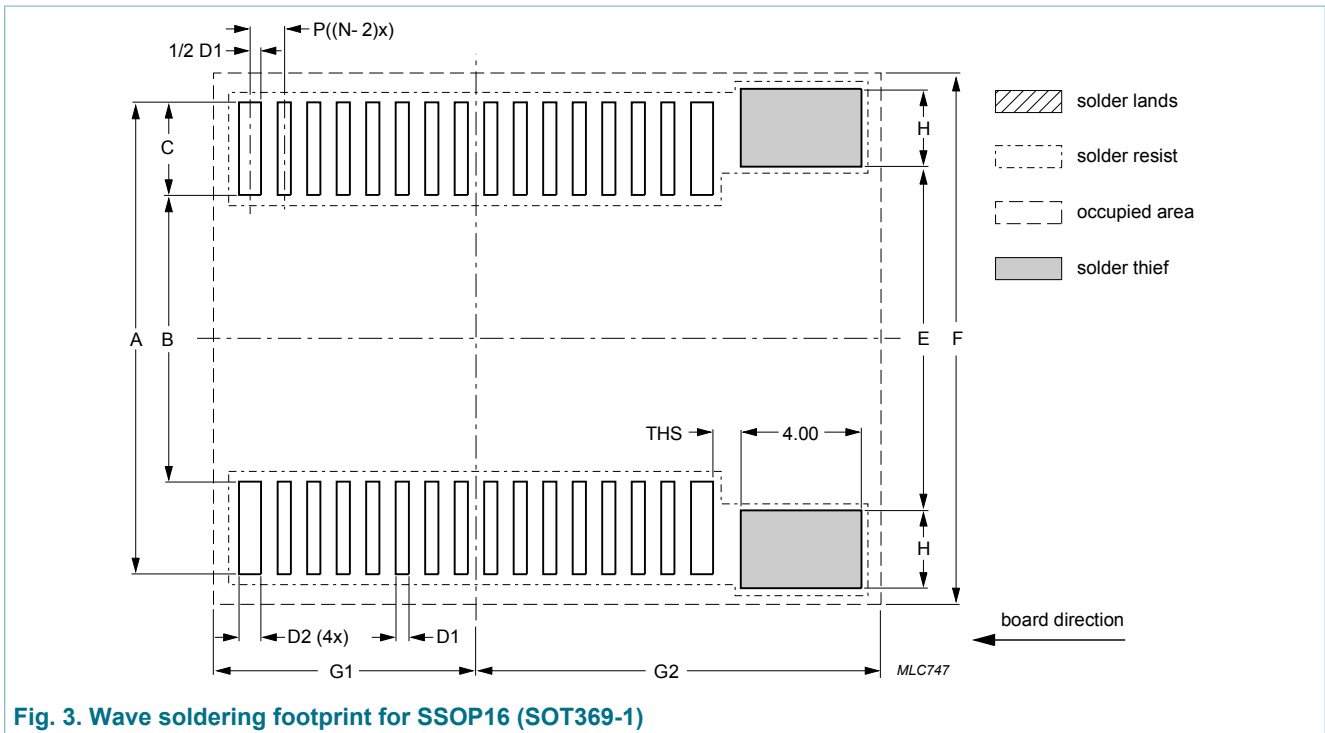


Fig. 3. Wave soldering footprint for SSOP16 (SOT369-1)

4. Legal information

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